

# 2SB0790 (2SB790)

## Silicon PNP epitaxial planar type

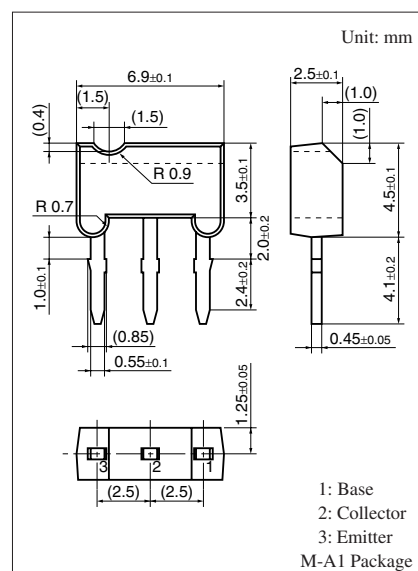
For low-frequency output amplification

### ■ Features

- Low collector-emitter saturation voltage  $V_{CE(sat)}$
- M type package allowing easy automatic and manual insertion as well as stand-alone fixing to the printed circuit board.

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter                             | Symbol    | Rating      | Unit             |
|---------------------------------------|-----------|-------------|------------------|
| Collector-base voltage (Emitter open) | $V_{CBO}$ | -25         | V                |
| Collector-emitter voltage (Base open) | $V_{CEO}$ | -20         | V                |
| Emitter-base voltage (Collector open) | $V_{EBO}$ | -7          | V                |
| Collector current                     | $I_C$     | -0.5        | A                |
| Peak collector current                | $I_{CP}$  | -1          | A                |
| Collector power dissipation           | $P_C$     | 600         | mW               |
| Junction temperature                  | $T_j$     | 150         | $^\circ\text{C}$ |
| Storage temperature                   | $T_{stg}$ | -55 to +150 | $^\circ\text{C}$ |



### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

| Parameter  | Symbol        | Conditions   | Min | Typ | Max  | Unit          |
|--|---------------|--|-----|-----|------|---------------|
| Collector-base voltage (Emitter open)                            | $V_{CBO}$     | $I_C = -10\ \mu\text{A}$ , $I_E = 0$                                     | -25 |     |      | V             |
| Collector-emitter voltage (Base open)                            | $V_{CEO}$     | $I_C = -1\ \text{mA}$ , $I_B = 0$  | -20 |     |      | V             |
| Emitter-base voltage (Collector open)                            | $V_{EBO}$     | $I_E = -10\ \mu\text{A}$ , $I_C = 0$                                     | -7  |     |      | V             |
| Collector-base cutoff current (Emitter open)                     | $I_{CBO}$     | $V_{CB} = -25\ \text{V}$ , $I_E = 0$                                     |     |     | -0.1 | $\mu\text{A}$ |
| Collector-emitter cutoff current (Base open)                     | $I_{CEO}$     | $V_{CE} = -20\ \text{V}$ , $I_B = 0$                                     |     |     | -1   | $\mu\text{A}$ |
| Forward current transfer ratio *1                                | $h_{FE1}$ *2  | $V_{CE} = -2\ \text{V}$ , $I_C = -0.5\ \text{A}$                         | 90  |     | 220  | —             |
|  | $h_{FE2}$     | $V_{CE} = -2\ \text{V}$ , $I_C = -1\ \text{A}$                           | 25  |     |      | —             |
| Collector-emitter saturation voltage *1                          | $V_{CE(sat)}$ | $I_C = -500\ \text{mA}$ , $I_B = -50\ \text{mA}$                         |     |     | -0.4 | V             |
| Base-emitter saturation voltage *1                               | $V_{BE(sat)}$ | $I_C = -500\ \text{mA}$ , $I_B = -50\ \text{mA}$                         |     |     | -1.2 | V             |
| Transition frequency   | $f_T$         | $V_{CB} = -10\ \text{V}$ , $I_E = 50\ \text{mA}$ , $f = 200\ \text{MHz}$ |     | 150 |      | MHz           |
| Collector output capacitance (Common base, input open circuited) | $C_{ob}$      | $V_{CB} = -10\ \text{V}$ , $I_E = 0$ , $f = 1\ \text{MHz}$               |     | 15  | 25   | pF            |

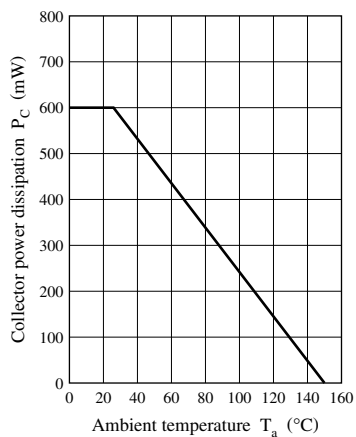
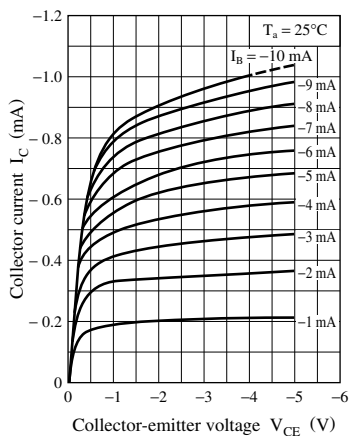
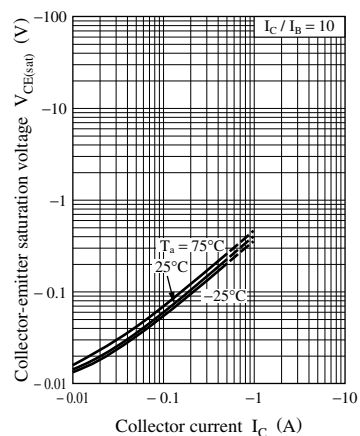
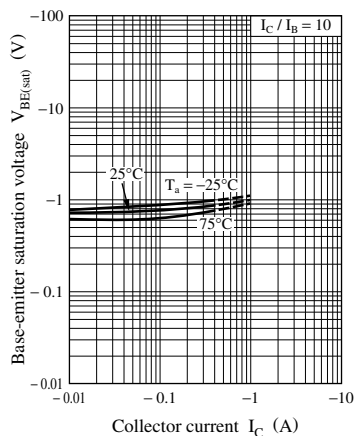
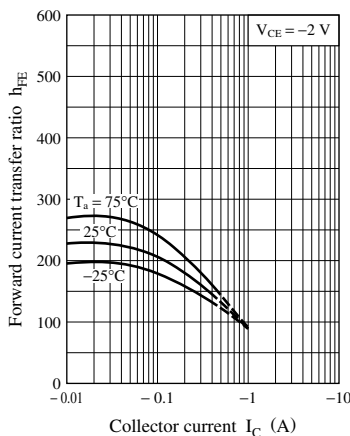
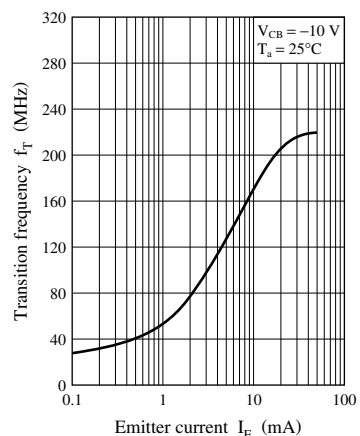
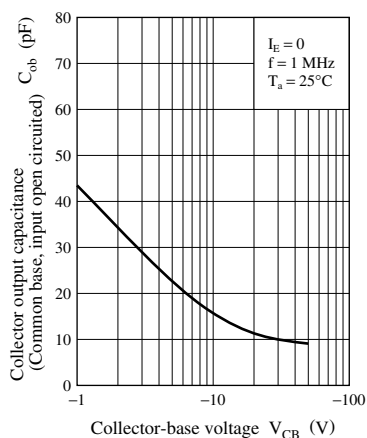
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. \*1: Pulse measurement

\*2: Rank classification

| Rank      | Q         | R          |
|-----------|-----------|------------|
| $h_{FE1}$ | 90 to 155 | 130 to 220 |

Note) The part number in the parenthesis shows conventional part number.

$P_C - T_a$  $I_C - V_{CE}$  $V_{CE(sat)} - I_C$  $V_{BE(sat)} - I_C$  $h_{FE} - I_C$  $f_T - I_E$  $C_{ob} - V_{CB}$ 

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